



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2016-02-24</b>
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Floriana San Biagio</b>	<b>Representative Title</b>	<b>AMG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*103AAA6	A	BO2A	2016-02-24
Amount	UoM	Unit type	ST ECOPACK Grade	
34.88	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.4x3x0.9	8	gull wing	
Comment	Package: 6P TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid for TSC103IPT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6P*103AAA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.196	mg	supplier	die	Silicon (Si)	7440-21-3		3.076	mg	962453	88188
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	6258	573
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	626	57
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	1877	172
				supplier	Passivation	Silicon Oxide	7631-86-9		0.035	mg	10951	1003
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.035	mg	10951	1003
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.022	mg	6884	631
Leadframe	Copper & its alloys	13.269	mg	supplier	alloy	Copper (Cu)	7440-50-8		12.167	mg	916949	348825
				supplier	alloy	Iron (Fe)	7439-89-6		0.286	mg	21554	8200
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.017	mg	1281	487
				supplier	alloy	Zinc (Zn)	7440-66-6		0.015	mg	1130	430
				supplier	metallization	Nickel (Ni)	7440-02-0		0.285	mg	21479	8171
				supplier	metallization	Palladium (Pd)	7440-05-3		0.018	mg	1357	516
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	603	229
Die attach	Other Organic Materials	0.754	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.473	mg	35647	13561
				supplier	glue	Silver (Ag)	7440-22-4		0.663	mg	879310	19008
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.038	mg	50398	1089
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.038	mg	50398	1089
				supplier	glue	Acrylate polymer	87320-05-6		0.015	mg	19894	430
				supplier	wire	Copper (Cu)	7440-50-8		0.065	mg	1000000	1864
				supplier	mold compound	Silica, vitreous	60676-86-0		15.431	mg	876961	442403
Bonding wires	Other inorganic materials	0.065	mg	supplier	mold compound	Epoxy resin	85954-11-6		0.704	mg	40009	20183
				supplier	mold compound	Epoxy	29690-82-2		0.704	mg	40009	20183
				supplier	mold compound	phenol resin	Proprietary		0.528	mg	30007	15138
				supplier	mold compound	additive	Proprietary		0.176	mg	10002	5046
				supplier	mold compound	carbon black	1333-86-4		0.053	mg	3012	1519
Encapsulation	Other Organic Materials	17.596	mg	supplier	mold compound	Silica, vitreous	60676-86-0		15.431	mg	876961	442403
				supplier	mold compound	Epoxy resin	85954-11-6		0.704	mg	40009	20183
				supplier	mold compound	Epoxy	29690-82-2		0.704	mg	40009	20183
				supplier	mold compound	phenol resin	Proprietary		0.528	mg	30007	15138
				supplier	mold compound	additive	Proprietary		0.176	mg	10002	5046
supplier	mold compound	carbon black	1333-86-4		0.053	mg	3012	1519				